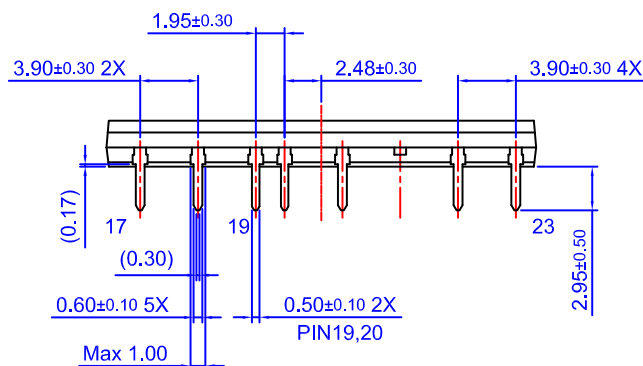
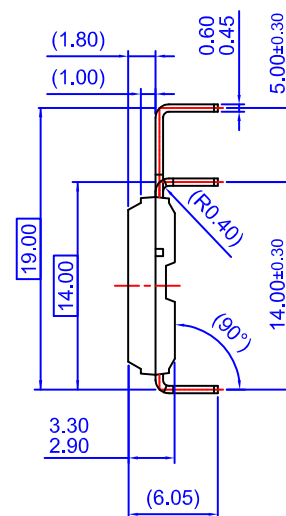
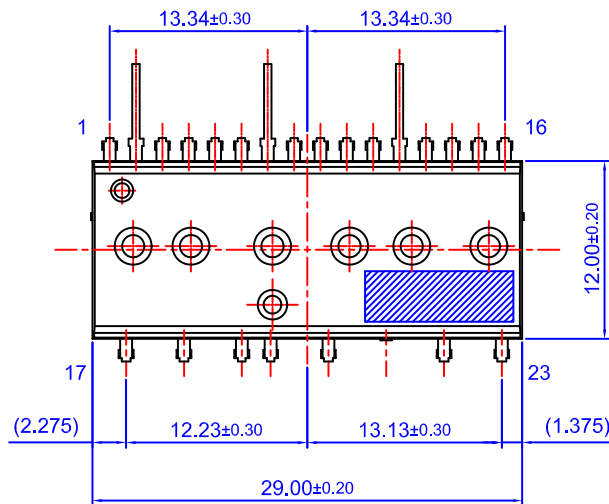
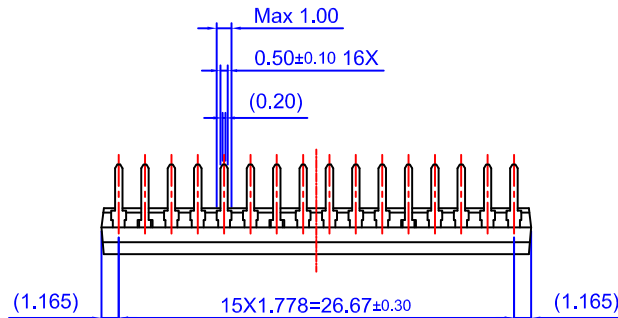


**SPM5G-023 / 23LD, PDD STD, FULL PACK, DOUBLE DIP TYPE (BSH)**  
CASE MODEL  
ISSUE O

DATE 31 JAN 2017



NOTES: UNLESS OTHERWISE SPECIFIED  
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B) ALL DIMENSIONS ARE IN MILLIMETERS  
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